



Type Document	Product Specification	Revised /Edition	L
Date Issued	2004/09/24	Data Revised	2020/12/18
Subject : JS-8254 JS-8001-T/TBP JS-6254-XX JS-7254-XX(L) JS-6255-XX Pitch : 2.54 mm Wire to Board Connector Series.			Issued By: Engineering Dept.

*This specification is referred to 2.54mm series wire to Board connector.*

本規格書內容係提供 2.54 mm 系列產品相關參考  
 , 其用途為電線端相接於電路板端連接器

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REV. (版次)	Revision Record (改版變更原因)	Date(日期)	ECN No
D	增加中文敘述 以及增加版次變更註記欄	2010/02/03	EC2010-02-003
E	鹽水噴霧週期以電鍍方式區隔為 8 小時與 48 小時	2011/05/30	EC2011-05-087
F	1.刪除硫化氫 2.修正(EIA-364) 參考規範 3.增列額定電壓 及電流與AWG對照	2012/04/17	EC2012-04-018
G	參照原廠規格修改 Insertion & Withdrawal Force : 嵌入力最大容許值 Insertion Force : 0.19kg/f Max ; 拔出力最小容許值 Retention Force : 0.057kg/f Min	2013/03/01	EC2013-03-001
H	參照實測平均值 6.1 Insertion Force 修訂為 0.7kg/f Max	2013/03/22	EC2013-03-022
I	1 增訂Wave Peak Soldering In- Process Temperature Profile 2.修訂Solder Ability 附註Tin Plated : 95% / Gold Plated : 75% 3.修訂 Wire Pullout Force(Axial)規格值	2013/12/09	EC2013-12-009
J	1.修訂8.9.1 項 Temperature Profile / 2增訂8.6 項Cold耐寒試驗	2015/02/24	EC2015-02-024
K	1增訂8.7項Salt Spray鹽水噴霧 2修改8.8項Solder Ability焊錫性 3更新BSI標示	2017/10/26	EC2017-10-026
L	Delete 8.9.1.2溫度曲線	2020/12/18	EC2020-12-014



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**1.0 Product Name/Part Number & Drawing Number(產品名稱 / 產品型號及圖面型號):**

Product Name(產品名稱)	Part Number(產品型號)	Drawing Number(圖面型號)
Crimp Terminal	JS-8001-T / JS-8001-PBT	
Housing	JS-8254-XX	
Wafer Straight ; with Peg (Color : White)	JS-6255-XXXXX	
Wafer Straight ; with Peg (Color : Red)	JS-6255-XXXXR	
Wafer Straight (Color : White)	JS-6254-XXXXW	
Wafer Straight (Color : Red)	JS-6254-XXXX	
Wafer Left Angle (Color : White)	JS-7254-XXXX(L)W	
Wafer Left Angle (Color : Red)	JS-7254-XXXX(L)	
Wafer Straight ; with Peg+ Glass Fiber(Color: White)	JS-6255-XX(GF) / JS-6255-XXXX	
Wafer Straight ; with Peg+ Glass Fiber(Color: Red)	JS-6255-XX(GF)R / JS-6255-XXXXR	

Note: (xx) The number of the circuits

**2.0 Construction/Dimensions/Material & Surface Finish(材質以及表面鍍層):**

Part Name(零件名稱)	Material(材質)	Surface Finish(表面鍍層)
Crimp Terminal (鉗壓端子)	JS-8001-T	Brass
	JS-8001-TBP	Phosphor Bronze
Housing (電線端連接器)	Nylon 66	Stamping after tin- plated (先電鍍後衝壓)
Wafer (電路板端連接器)	Square pin (方型導體)	UL 94V-0
	Base (膠座)	Brass Nylon 66 or Nylon 66+Glass
		Tin-Plated UL 94V-0

**3.0 Characteristic(產品特性):**

Item(項目)	Standard(標準規範)					
3.1 額定電流 Rated Current	Conductor Size	AWG	22#	24#	26#	28#
		Area(mm <sup>2</sup> )	0.342 mm <sup>2</sup>	0.220 mm <sup>2</sup>	0.14 mm <sup>2</sup>	0.089 mm <sup>2</sup>
	Amp AC/DC		3 A	2 A	1 A	0.8 A
3.2 額定電壓 Rated Voltage	125 V AC/DC					
3.3 Ambient Temperature Range 環境與操作溫度範圍	(操作使用溫度與濕度範圍) Operating Temp.: -25°C ~+85°C ; 85% R.H. Max Including 30°C Terminal Temperature Rise at rated Current , (包括定額電流內, 端子所產生 30°C 以下溫昇)					
3.4 Applicable Wire 適用電線	3.4.1	(金屬導體型號) Conductor Construction Size: AWG #22~#28				
	3.4.2	(電線絕緣材質外徑) Wire Insulation O.D.: 1.15mm~1.90mm				
3.5 Storage of Package 包裝未拆封之保存	Temperature and Humidity Condition 溫濕度條件			Temperature 溫度 : -10°C~+40°C Percentage Humidity 相對濕度 : 70 % Max		
	Term 保存期限	Housing		2 Years		
		Crimp Terminal & Wafer		1 Year		



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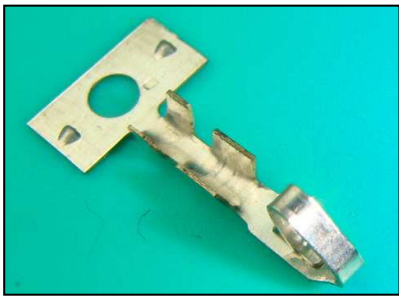
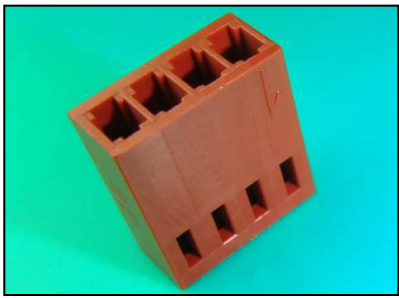
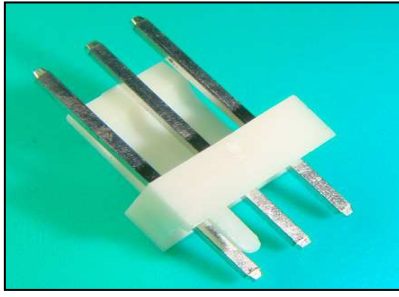
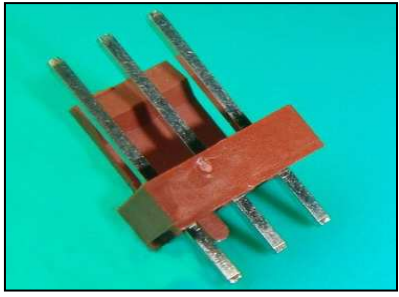
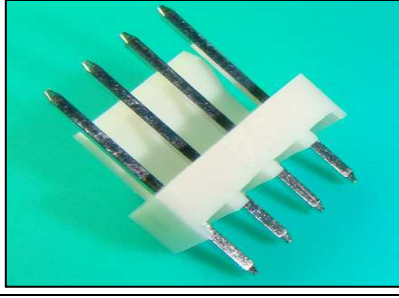
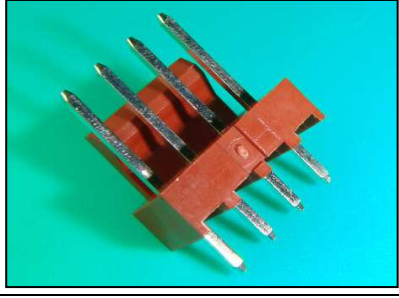
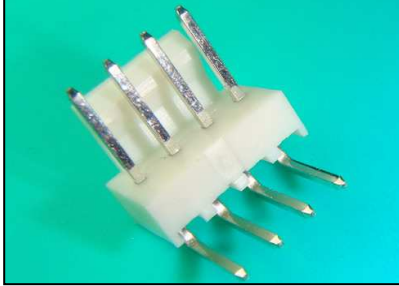
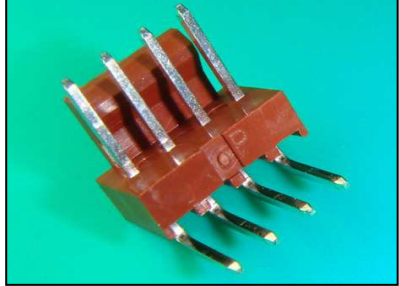
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<b>3.6</b>	<b>Floor Life 拆封後使用期限</b>	<b>Crimp Terminal &amp; Wafer</b>	<b>3 Months</b>

Note: 適用電路板厚度 Applicable Printed Circuit Board Thickness: 1.6 mm

**4.0 Specimen(樣本圖示) :**

Part Name / Part Number / Picture or Photograph 零件名稱 / 零件型號 / 樣本圖示			
<b>Crimp Terminal</b>  JS-8001-T  JS-8001-PBT		<b>Housing</b>  JS-8254-XX	
<b>Wafer Straight</b>  with Peg  JS-6255-XX		<b>Wafer Straight</b>  with Peg  JS-6255-XXR	
<b>Wafer</b>  <b>Straight</b>  JS-6254-XXW		<b>Wafer</b>  <b>Straight</b>  JS-6254-XX	
<b>Wafer</b>  <b>Left Angle</b>  JS-7254-XX(L)W		<b>Wafer</b>  <b>Left Angle</b>  JS-7254-XX(L)	

**5.0 Applicable Standards(適用規範):**

ANSI/EIA 364 ; EIA/ECA 364 Testing method for electrical connectors.

電子連接器，所適用之 ANSI/EIA 364 ; EIA/ECA 364 測試規範



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**6.0 Mechanical Performance(機械性能):**

Item(項目)		Test Condition(測試條件)	Requirement(規格)
6.1	<b>Insertion &amp; Withdrawal Force</b> 嵌入力與拔出力	Insert and withdrawal with connectors at the speed rate of 25.4 ± 3 mm /minute. 連接器兩端勘合，以每一分鐘25.4 ± 3mm的速率，作嵌入與拔出往返測試 (EIA/ECA 364-13D) <b>(Excluding Plastic Detent 不包含膠座卡榫結合力)</b>	單一接觸點 Per Contact 嵌入力最大容許值： <b>Insertion Force 0.7kg/f Max</b> 拔出力最小容許值： <b>Withdrawal Force 0.06kg/f Min</b>
6.2	<b>Wire Pullout Force(Axial)</b> 電線脫離端子包覆之拔出力(軸向)	Pull out the cable from contact terminal at the speed rate of 25.4± 3 mm/minute. 對端子所包覆電線，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出 力 (EIA 364-08B)	<b>AWG#22 size wire 4.48kgf/Min.(44.0N 牛頓)</b>
			<b>AWG#24 size wire 3.57kgf/Min.(35.0N 牛頓)</b>
			<b>AWG#26 size wire 2.65kgf/Min.(26N 牛頓)</b>
			<b>AWG#28 size wire 1.73kgf/Min.(17N 牛頓)</b>
6.3	<b>Crimp Terminal Retention Force ( in Housing )</b> 柳線端子與膠座間拔出力	<b>Axial pullout force on the terminal in the housing at the speed rate of 25.4 ± 3 mm per minute. 對於已經存在於膠座當中柳線端子，施以每一分鐘 25.4± 3 mm 速率之軸向拔出力 (EIA 364-05)</b>	單一接觸點 Per Contact 最小容許值 <b>1.8kgf/Min.</b>
6.4	<b>Square Pin Retention Force ( in Base )</b> 方型導體與膠座間保持力	<b>Axial pullout force on the square pin in the base at the speed rate of 25.4 ± 3 mm per minute. 對於已經存在於膠座當中方型導體，施以每一分鐘 25.4 ± 3 mm 速率之軸向拔出力 (EIA/ECA 364-29C )</b>	單一接觸點 Per Contact 最小容許值 <b>1.5kgf/Min.</b>

**7.0 Electrical Performance(電氣性能):**

Item(項目)		Test Condition(測試條件)	Requirement(規格)
7.1	<b>(Low –Signal Level) Contact Resistance</b> (低階信號) 接觸阻抗	<b>A maximum voltage of 20mV and a maximum current of 100mA are applied to the mate connector. 對組合狀態下連接器，於其兩端施以最大測試電壓 20mV 以及最大測試電流 100mA (EIA/ECA 364-23C)</b> <b>( Does not include wire resistance 不包含電線阻抗 )</b>	<b>Contact Resistance:</b> <b>20 milliohms Max.</b> 最大容許值. 20 毫歐姆
7.2	<b>Insulation Resistance</b> 絕緣阻抗	<b>Apply 500V D/C for 1 minute between adjacent contacts to measure the insulation resistance. 對相鄰兩接觸導體，於一分鐘時間內施予 500V D/C 電壓，並量測其間絕緣阻抗值 (EIA 364-21C)</b>	<b>Insulation Resistance:</b> <b>Initial 1000megohms Min</b> 最初容許值. 1000 兆歐姆



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Item(項目)	Test Condition(測試條件)	Requirement(規格)
7.3 Withstanding Voltage 耐電壓	Apply <b>1000 A/C (rms)</b> for 1 minute and the leakage current shall not exceed <b>0.5mA</b> to the adjacent terminal and ground of the mate connectors. 對組合狀態下連接器，於其相鄰兩導體末端各施以電壓 <b>1000 A/C</b> (實效值) 時間 1 分鐘，且漏電流必須小於 <b>0.5mA</b> (毫安培) (EIA 364-20C)	No breakdown or flashover. 無損毀或者產生火花

8.0 Environmental Performance(環境性能) :

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.1 Temperature Rise (Via Current Cycling) 溫度上昇 (經由電流循環操作)	Mate connector . measure the temperature rise of contact when the maximum rated current is passed 以組合狀態下連接器，通過最大容許電流 量測其導體溫度上昇值 (EIA 364-70B Conditions 1 . Method 1)	Mate connectors <b>Temperature Rise:</b> <b>+30°C/Max.</b> 組合狀態下之連接器溫度 上昇最大容許值 +30°C
8.2 Vibration 耐振動	A mated connector shall be mounted on a printed Circuit board and subjected to a vibration test of the following conditions. During the test, test current continuity shall be checked. After the test, contact resistance shall be measured. 以組合狀態下連接器焊接於電路板作為試驗樣品,依照隨附如下規格要求,進行耐振動試驗，試驗過程中確認是否產生不連續電流(斷電)現象，並於試驗過後量測其接觸阻抗。 (EIA/ECA 364-28E-Condition 1 ) Frequency(頻率) : 10~55~10 Hz/minute. Amplitude (振幅) : 1.5 mm P-P Direction (方向) :1. Axis of up and down.上下軸向(Y 軸) 2. Axis of right the left. 左右軸向(X 軸) 3. Axis of front and back.前後軸向(Z 軸) Period(週期) : 2 hours for each direction. (每一個軸向持續 2 小時)	Initial Contact Resistance : <b>20 milliohms Max.</b> 接觸阻抗最初容許值 20 毫歐姆 (After the test) Contact Resistance: <b>40 milliohms Max.</b> 經耐振動試驗後接觸阻抗 最大容許值 40 毫歐姆  No discontinuity current is longer than 1 microsecond. 電流中斷現象， 時間不可多於1微秒



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8.3	Humidity (Steady State) 恆溫恆濕	<p>A mated connector shall be placed in a humidity chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.            (EIA 364-31B Conditions II. Method A)            以組合狀態下連接器放置於恆定溫度與濕度的空間, 依照隨附如下規格要求, 進行恆溫恆濕試驗, 經試驗過後將樣品置於室溫 1~2 小時, 再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。  <b>Temperature(溫度) : 40±2°C.</b>  <b>Relative Humidity(相對濕度) : 90%~95% (RH).</b>  <b>Period(週期) : 96 hours continuously. (持續 96 小時)</b></p>	<p>(After the test)  <b>Contact Resistance:</b>  <b>40 milliohms Max.</b>            經恆溫恆濕試驗後接觸阻抗            最大容許值. 40 毫歐姆</p>
			<p>(After the test)  <b>Insulation Resistance :</b>  <b>500 Megohms Min.</b>            經恆溫恆濕試驗後絕緣阻抗            最小容許值. 500 兆歐姆</p>
			<p>經恆溫恆濕試驗後測耐電壓            (After the test)  <b>Withstanding Voltage:</b>  <b>1000V A/C for 1 minute</b></p>
8.4	Thermal Shock 冷熱衝擊	<p>A mated connector shall be subjected to a thermal shock test of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance, the insulation resistance and the dielectric withstanding voltage shall be measured.            以組合狀態下連接器作為試驗樣品, 依照隨附如下規格要求, 進行冷熱衝擊試驗, 經試驗過後將樣品置於室溫 1~2 小時, 再量測其接觸阻抗、絕緣阻抗、以及耐電壓測試。            (EIA/ECA 364-32D Conditions I. Method A)  <b>One Cycle Consists Of:</b>  <b>-55°C+0/-3°C for 30 minutes. → Room Temp. 5 minutes</b>  <b>85°C+3/-0°C for 30 minutes. → Room Temp. 5 minutes</b>  <b>Total Cycles: 5 Cycles.</b>            以 -55°C +0/-3°C 溫度持續 30 分鐘, 經室溫 5 分鐘, 而後再以 85°C +3/-0°C 溫度持續 30 分鐘, 再經室溫 5 分鐘, 構成一次冷熱循環, 總計循環次數 5 次。</p>	<p><b>Same as paragraph 8.3</b>            同 8.3 章節</p>



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<b>Pitch : 2.54 mm Wire to Board Connector Series.</b>			

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.5 Thermal Aging 高溫老化試驗	<p>A mated connector shall be placed in a heat oven of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. 以組合狀態下連接器放置於加熱烤箱當中，依照隨附如下規格要求，進行高溫老化試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗。(EIA 364-17B Conditions 3 . Method A )</p> <p>Temperature(溫度) : 85±2°C.</p> <p>Period(週期): 96 hours continuously . (持續 96 小時)</p>	<p>Initial Contact Resistance : 20 milliohms Max. 接觸阻抗最初容許值 20 毫歐姆</p> <p>(After the test)</p> <p>Contact Resistance : 40 milliohms Max. . 經高溫老化試驗後接觸阻抗 最大容許值. 40 毫歐姆</p>
8.6 Cold 耐寒試驗 (Low Temperature)	<p>A mated connector shall be placed in a cold chamber of the following conditions. After the test, leave the specimen at room temperature for 1~2 hours before the contact resistance shall be measured. 以組合狀態下連接器放置於低溫空間內，依照隨附如下規格要求，進行耐寒試驗，經試驗過後將樣品置於室溫 1~2 小時，再量測其接觸阻抗。(EIA 364-59A Procedure 4)</p> <p>Temperature(溫度) : -25±3°C.</p> <p>Period(週期): 96 hours continuously . (持續 96 小時)</p>	<p>Initial Contact Resistance : 20 milliohms Max. 接觸阻抗最初容許值 20 毫歐姆</p> <p>(After the test)</p> <p>Contact Resistance : 40 milliohms Max. . 經耐寒試驗後接觸阻抗 最大容許值. 40 毫歐姆</p>
8.7 Salt Spray 鹽水噴霧	<p>A mated connector shall be subjected to a Salt Spray test of the following conditions. After the test , the specimen shall be washed with running water and dried naturally before the measurement of contact resistance. 以組合狀態下連接器作為試驗樣品，依照隨附如下規格要求，進行鹽水噴霧試驗，試驗過後將樣品用清水沖洗並經過自然風乾，而後量測其接觸阻抗。</p> <p>Density(鹽水密度): 5 % in weight. Temperature(溫度): 35±2°C.</p> <p>Period(週期): <b>Terminal or contact (Stamping after tin plated for 8 hours) ; Terminal or contact (Stamping before tin plated for 48 hours)</b>  <b>端子或導體(先電鍍後沖壓 8 小時) ; 端子或導體 (先沖壓後電鍍 48 小時)</b>            (EIA 364-26B Conditions B)</p> <p>Salt spray test only define the plating area,without plating area (as copper cross section) will not be defined. 鹽水噴霧測試只判定電鍍區域,無電鍍區域(如折斷面裸銅)則不做判定</p>	<p>Initial Contact Resistance : 20 milliohms Max. 接觸阻抗最初容許值 20 毫歐姆</p> <p>(After the test)</p> <p>Contact Resistance: 40 milliohms Max. 經鹽水噴霧試驗後接觸阻抗 最大容許值. 40 毫歐姆</p>



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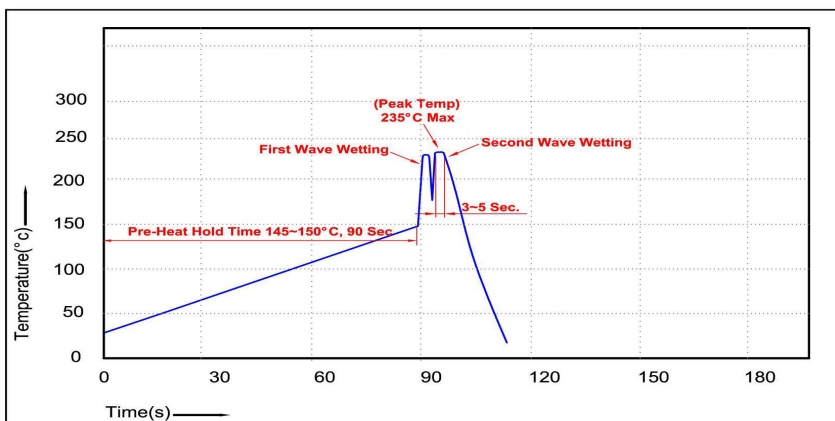
<b>Type Document</b>	<b>Product Specification</b>	<b>Revised /Edition</b>	<b>L</b>
<b>Date Issued</b>	<b>2004/09/24</b>	<b>Data Revised</b>	<b>2020/12/18</b>
<b>Subject : JS-8254 JS-8001-T/TBP JS-6254-XX JS-7254-XX(L) JS-6255-XX</b>			<b>Issued By:</b>
<b>Pitch : 2.54 mm Wire to Board Connector Series.</b>			<b>Engineering Dept.</b>

Item(項目)	Test Condition(測試條件)	Requirement(規格)
8.8 Solder Ability 焊錫性	Fluxed soldering section of header shall be dipped in solder of the following conditions. 將連接器 pin 針基板嵌入端，接觸熱溶狀錫料，依照隨附如下規格要求，進行焊錫性試驗 (EIA 364-52B) Solder Temperature (焊錫溫度) : <b>245 ± 5°C.</b> Immersion Period (沉浸週期) : <b>3±0.5 Seconds</b> (操作方式) : 零件焊錫位置，距離導體末端 <b>1.5mm</b> Method : <b>1.5mm from square pin tip</b>	Solder entirely <b>95%</b> of immersed area must show no voids or pinholes. 焊料覆蓋面積必須達到 <b>95%</b> ，而且不能產生氣孔或空隙
8.9 Resistance to Soldering Heat 焊錫耐熱性	Resistance to soldering : 承受焊錫耐熱範圍 : Refer to Temperature Profile 請參考 <b>8.9.1.1</b> 溫度曲線圖 By soldering iron 手工烙鐵焊錫適用溫度範圍 : <b>350 ± 5°C 3±0.5 Seconds.</b> Method : <b>1.5mm from square pin tip</b> (EIA/ECA 364-56C Procedure 3. Conditions A)	No deformation or damage. 不可有變形或損壞

Notes : Flowing Mixed Gas (EIA 364-65A) shall be conduct by Customer request 混合流動氣體測試遵照客戶需求

**8.9.1 Temperature Profile(溫度曲線圖) :**

**8.9.1.1 Wave Peak Soldering In- General Process 波焊一般制程**



**9.0 Remark(備註) : Any change or revision for the product specification will not be announced in advance.**

Please contact our sales representative for the latest information.

有關規格書內容經變更或改版，如未能夠及時發佈與通知，煩請連絡我司業務人員以提供產品最新資訊

**Reviewed:** Tom Shih **Approved:** Tom Shih **Verified:** Erin Chou